

保密等级：机密

SPECIFICATION

产品规格书

SKO.WB663U.16 B24333

IEEE 802.11b/g/n/a/ac 2T2R USB WiFi Module

Integrated BT 2.1+EDR/4.2/5.1

Approved by Shikun		
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苏豪		

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REVISION HISTORY

VERSION	DATE	BOARD ID	PAGE	DESCRIPTION	AUTHOR
V1.0	2024.8.28	SKO.WB663U.16	All	First Issued	SUHAO
V1.1	2024.11.19	SKO.WB663U.16	3	自然切换	SUHAO
V1.2	2024.12.9	SKO.WB663U.16	5	自然切换	SUHAO
V1.3	2025.1.21	SKO.WB663U.16	19.20	自然切换	SUHAO

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1. Introduction（简介）

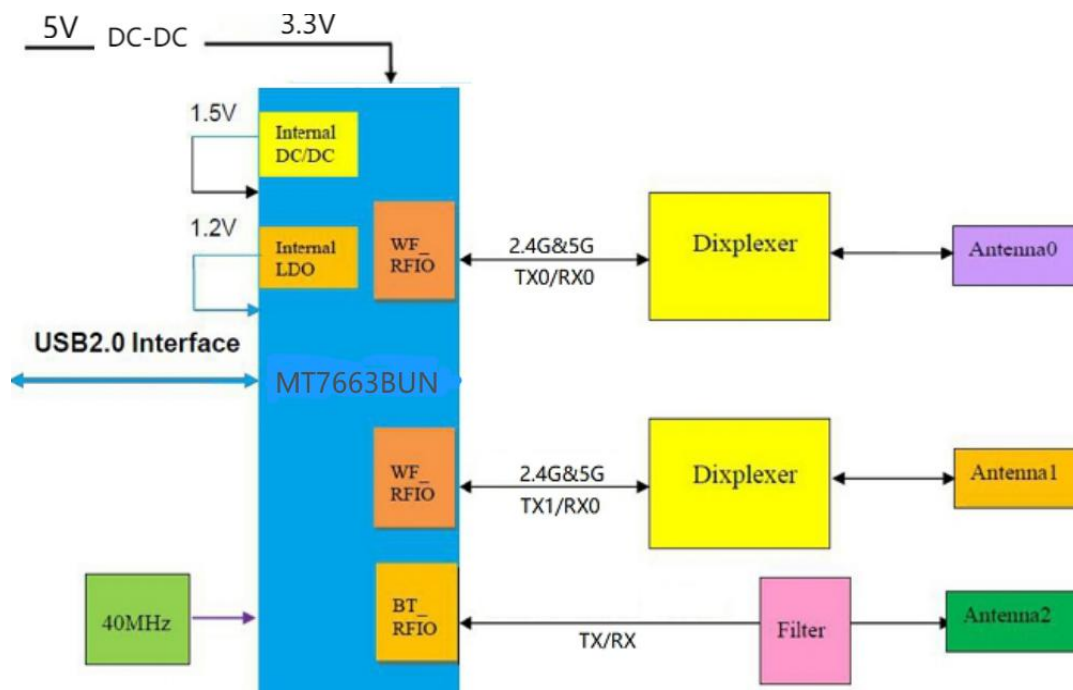
SKO.WB663U.16 module is based on MediaTek MT7663BUN solution. MT7663BUN is highly integrated single chip which features a low power 2x2 11a/b/g/n/ac dual-band Wi-Fi subsystem and a Bluetooth subsystem. The Wi-Fi subsystem contains the 802.11a/b/g/n/ac radio, baseband, and MAC that are designed to meet both the low power and high throughput application. MT7663BUN has a 32-bit RISC MCU that handles Wi-Fi and Bluetooth tasks. The Bluetooth subsystem contains the Bluetooth radio, baseband, link controller. It also uses the 32-bit RISC MCU for the Bluetooth protocols. This documentation describes the engineering requirements specification.

SKO.WB663U.16 模块基于 MEDIATEK MT7663BUN 解决方案。MT7663BUN 是高度集成的单芯片，具有低功耗 2x2 11a/b/g/n/ac 双频 Wi-Fi 子系统和蓝牙子系统。Wi-Fi 子系统包含 802.11a/b/g/n/ac 无线电，基带和 MAC 旨在满足低功耗和高吞吐量应用。MT7663BUN 有一个 32 位 RISC MCU，可处理 Wi-Fi 和蓝牙任务。蓝牙子系统包含蓝牙无线电、基带、链路控制器。它还使用 32 位 RISC MCU 来实现蓝牙协议。本文件描述了工程需求规范。

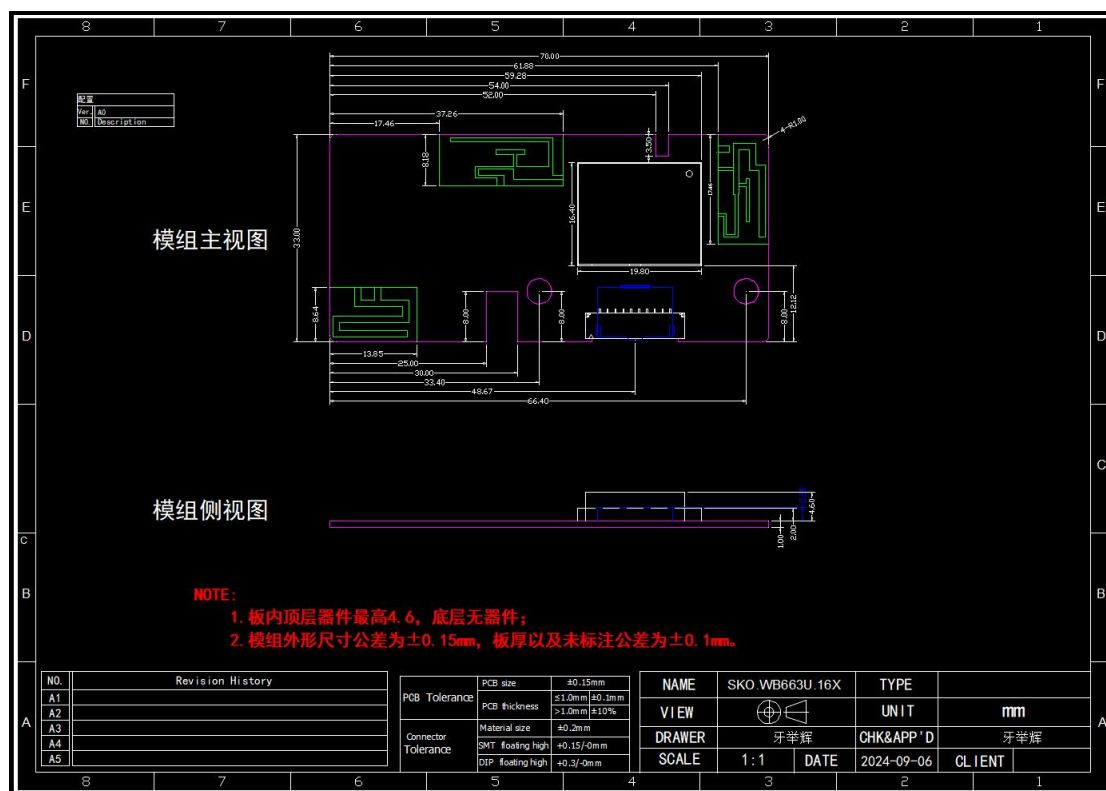
2. Features（特性）

Reserving System 接收制式	IEEE Std. 802.11a
	IEEE Std. 802.11b
	IEEE Std. 802.11g
	IEEE Std. 802.11n
	IEEE Std. 802.11ac
	Bluetooth 2.1+EDR/3.0/4.x/5.1
Chip Solution 芯片方案	MT7663BUN
Band 波段	2.4GHz/5GHz
Dimensions 尺寸	70mm×33mm×2.7mm
Bandwidth 带宽	20/40/80MHz
Antenna 天线	板载*3

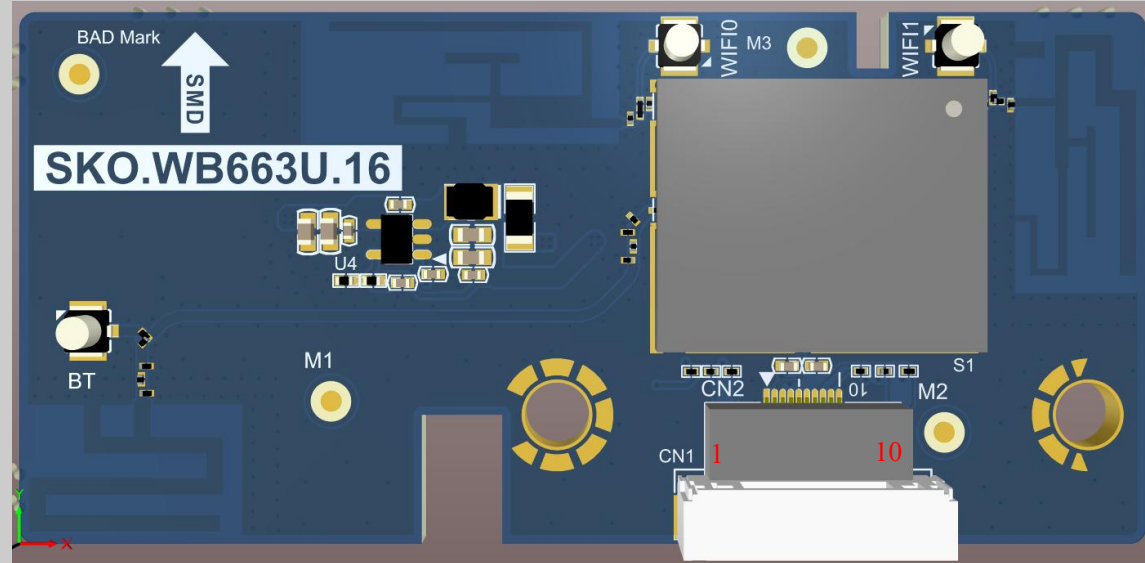
3. Block Diagram (结构框图)



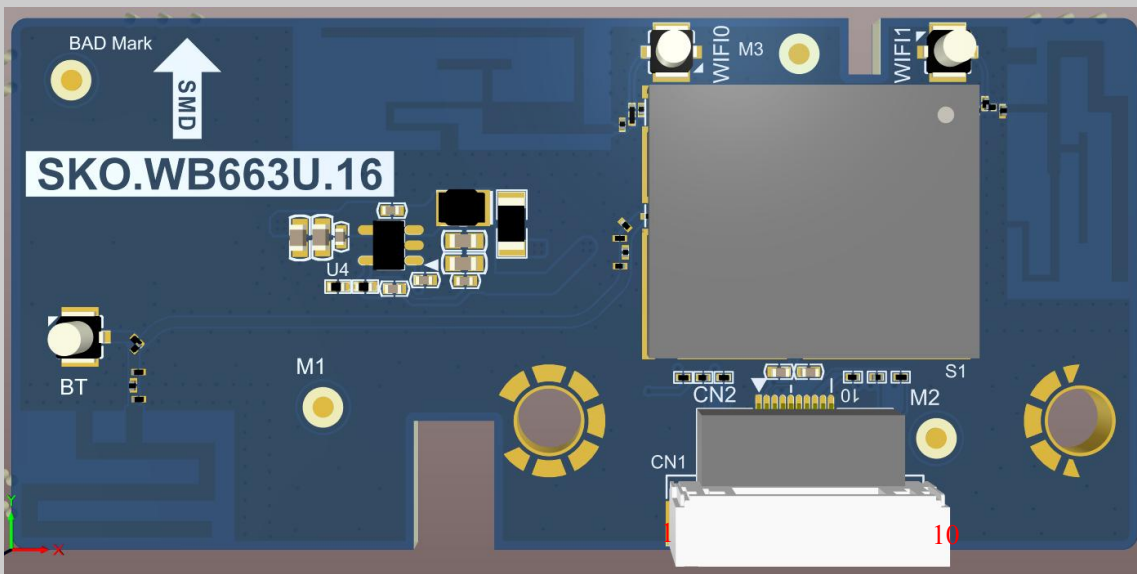
4. Package Outline and Mounting (外形及安装尺寸)



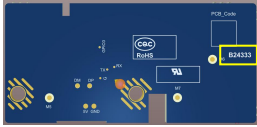
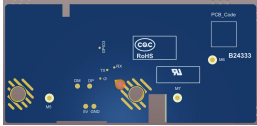
5. Pin Definition (引脚定义)

Bottom VIEW				
				
PIN	SYMBOL	Type	I/O Level	DESCRIPTION
1	GND	P	/	GND/接地
2	USB 2.0-DP	AI/O	/	USB_2.0 DP 引脚
3	USB 2.0-DM	AI/O	/	USB_2.0 DM 引脚
4	5V_STB	P	/	DC 5.0V Main power supply
5	5V_STB	P	/	DC 5.0V Main power supply
6	5V_STB	P	/	DC 5.0V Main power supply
7	WI_WAKE	O	3.3V	WLAN_wake up host
8	BT_WAKE	O	3.3V	BT_wake up host
9	RESET	I	3.3V	System reset Input, active low
10	GND	P	/	GND/接地

*:P: Power or Ground; I/O: In/Output; I: Input; A I/O: Analog In/Output; AI: Analog Input;
AO: Analog Output; RF: Analog RF Port or RF Ground;

Bottom VIEW				
				
PIN	SYMBOL	Type	I/O Level	DESCRIPTION
1	DC_EN	I	5V	The board DC / DC enable active high input
2	BT_WAKE	O	3.3V	Bluetooth_wake up host
3	5V_STB	P	/	DC 5.0V Main power supply
4	NetCN1_4	AI/O	/	USB 2.0-DM
5	NetCN1_5	AI/O	/	USB 2.0-DP
6	GND	P	/	GND/接地
7	GND	P	/	GND/接地
8	3D_SYNC	O	3.3V	Synchronization function
9	RESET	I	3.3V	System reset Input, active low
10	WI_WAKE	O	3.3V	WLAN_wake up host

6. Product Pictures（实物图片）

模组料号	正视图	背视图	备注
002.029.0001436			CN1
002.029.0001501			CN2

丝印说明：

- （1）正视图内红色方框处的字符为产品型号
- （2）背视图内黄色方框处的字符为产品周期号

7. Key Materials（关键物料）

序号	关键件名称	型号	规格/材料	备注
1	集成电路	MT7663BUN	QFN-76	
2	PCB	SKO.WB663U.16	FR-4,4LAY	
3	晶体振荡器	40MHz,±10ppm,3225	40MHz	MDH
4	双工器	FLT18D254959D-3206A	2400~2500MHz 0.5db 4900~5950MHz 0.7db	FTR

8. General Requirements（一般要求）

No.	Feature	Description
8-1	Operation Voltage 工作电压范围	5.0V+/-0.5
8-2	Current Consumption 最大电流	1000mA
8-3	Ripple 纹波	≤10%
8-4	Operation Temperature 工作温度范围	-10°C to +70°C
8-5	Antenna Type 天线类型	Internal antenna/Stamp Hole
8-6	USB	High Speed USB 2.0 Interface
8-7	Storage Temperature 存储温度	-40°C to +85°C

9. Electrical Characteristics（电气特性）

除非另有说明，电气规范试验都在下列条件下进行：

环境条件温度：25°C ± 5°C；

电源电压：模块上输入电压 5V+/-0.5；

The Test for electrical specification was performed under the following condition unless otherwise specified:

Ambient condition Temperature :25°C ± 5°C；

Power supply voltages: 5V+/-0.5 input power at the Module;

9.1 IEEE 802.11b Section

Items	Contents				
Specification	IEEE802.11b				
Mode	CCK				
Channel	CH1 to CH13				
Data rate	1, 2, 5.5, 11Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	Remark
1. Power Levels(Calibrated)					
1) For antenna port	15	17	19	dBm	
2. Spectrum Mask @ target power					

1) fc +/-11MHz to +/-22MHz	-	-	-30	dBr	
2) fc > +/-22MHz	-	-	-50	dBr	
3 Constellation Error(EVM)@ target power					
1) 1Mbps	-	-	-10	dB	
2) 2Mbps	-	-	-10	dB	
3) 5.5Mbps	-	-	-10	dB	
4) 11Mbps	-	-	-10	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5 Minimum Input Level Sensitivity (each chain)					
1) 1Mbps (FER ≤8%)	-	-	-83	dBm	
2) 2Mbps (FER ≤8%)	-	-	-80	dBm	
3) 5.5Mbps (FER ≤8%)	-	-	-79	dBm	
4) 11Mbps (FER ≤8%)	-	-	-76	dBm	
6 Maximum Input Level (FER ≤8%)	-10	-	-	dBm	

9.2 IEEE 802.11g Section

Items	Contents				
Specification	IEEE802.11g				
Mode	OFDM				
Channel	CH1 to CH13				
Data rate	6, 9, 12, 18, 24, 36, 48, 54Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	Remark
1. Power Levels					
1) For antenna port	13	15	17	dBm	
2. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-40	dBr	
3 Constellation Error(EVM)@ target power					
1) 6Mbps	-	-	-5	dB	
2) 9Mbps	-	-	-8	dB	
3) 12Mbps	-	-	-10	dB	
4) 18Mbps	-	-	-13	dB	
5) 24Mbps	-	-	-16	dB	
6) 36Mbps	-	-	-19	dB	
7) 48Mbps	-	-	-22	dB	
8) 54Mbps	-	-	-25	dB	
4 Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	

5 Minimum Input Level Sensitivity (each chain)					
1) 6Mbps (PER $\leq 10\%$)	-	-	-85	dBm	
2) 9Mbps (PER $\leq 10\%$)	-	-	-84	dBm	
3) 12Mbps (PER $\leq 10\%$)	-	-	-82	dBm	
4) 18Mbps (PER $\leq 10\%$)	-	-	-80	dBm	
5) 24Mbps (PER $\leq 10\%$)	-	-	-77	dBm	
6) 36Mbps (PER $\leq 10\%$)	-	-	-73	dBm	
7) 48Mbps (PER $\leq 10\%$)	-	-	-69	dBm	
8) 54Mbps (PER $\leq 10\%$)	-	-	-65	dBm	
6 Maximum Input Level (PER $\leq 10\%$)	-20	-	-	dBm	

9.3 IEEE 802.11n HT20 Section

Items	Contents				
Specification	IEEE802.11n HT20 @ 2.4GHz				
Mode	OFDM				
Channel	CH1 to CH13				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels					
1) For antenna port	12	14	16	dBm	
2. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-45	dBr	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER $\leq 10\%$)	-	-	-82	dBm	
2) MCS1 (PER $\leq 10\%$)	-	-	-79	dBm	
3) MCS2 (PER $\leq 10\%$)	-	-	-77	dBm	

4) MCS3 (PER $\leq 10\%$)	-	-	-74	dBm	
5) MCS4 (PER $\leq 10\%$)	-	-	-70	dBm	
6) MCS5 (PER $\leq 10\%$)	-	-	-66	dBm	
7) MCS6 (PER $\leq 10\%$)	-	-	-65	dBm	
8) MCS7 (PER $\leq 10\%$)	-	-	-64	dBm	
7. Maximum Input Level (PER $\leq 10\%$)	-20	-	-	dBm	

9.4 IEEE 802.11n HT40 Section

Items	Contents				
Specification	IEEE802.11n HT40 @ 2.4GHz				
Mode	OFDM				
Channel	CH3 to CH11				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For antenna port	12	14	16	dBm	
2. Spectrum Mask @target power					
1) at fc +/-22MHz	-	-	-20	dBm	
2) at fc +/-40MHz	-	-	-28	dBm	
3) at fc > +/-60MHz	-	-	-45	dBm	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER $\leq 10\%$)	-	-	-79	dBm	
2) MCS1 (PER $\leq 10\%$)	-	-	-76	dBm	
3) MCS2 (PER $\leq 10\%$)	-	-	-74	dBm	
4) MCS3 (PER $\leq 10\%$)	-	-	-71	dBm	
5) MCS4 (PER $\leq 10\%$)	-	-	-67	dBm	
6) MCS5 (PER $\leq 10\%$)	-	-	-63	dBm	
7) MCS6 (PER $\leq 10\%$)	-	-	-62	dBm	
8) MCS7 (PER $\leq 10\%$)	-	-	-61	dBm	

6. Maximum Input Level (PER $\leq 10\%$)	-20	-	-	dBm	
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9.5 IEEE 802.11a Section

Items	Contents				
Specification	IEEE802.11a				
Mode	OFDM				
Channel	CH36 to CH165				
Data rate (MCS index)	6, 9, 12, 18, 24, 36, 48, 54Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For antenna port	13	15	17	dBm	
2. Spectrum Mask @target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-40	dBr	
3. Constellation Error(EVM)@ target power					
1) 6Mbps	-	-	-5	dB	
2) 9Mbps	-	-	-8	dB	
3) 12Mbps	-	-	-10	dB	
4) 18Mbps	-	-	-13	dB	
5) 24Mbps	-	-	-16	dB	
6) 36Mbps	-	-	-19	dB	
7) 48Mbps	-	-	-22	dB	
8) 54Mbps	-	-	-25	dB	
4 Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5 Minimum Input Level Sensitivity (each chain)					
1) 6Mbps (PER $\leq 10\%$)	-	-	-82	dBm	
2) 9Mbps (PER $\leq 10\%$)	-	-	-81	dBm	
3) 12Mbps (PER $\leq 10\%$)	-	-	-79	dBm	
4) 18Mbps (PER $\leq 10\%$)	-	-	-77	dBm	
5) 24Mbps (PER $\leq 10\%$)	-	-	-74	dBm	
6) 36Mbps (PER $\leq 10\%$)	-	-	-70	dBm	
7) 48Mbps (PER $\leq 10\%$)	-	-	-66	dBm	
8) 54Mbps (PER $\leq 10\%$)	-	-	-65	dBm	
6. Maximum Input Level (PER $\leq 10\%$)	-30	-	-	dBm	

9.6 IEEE 802.11n HT20 Section(5GHz)

Items	Contents				
Specification	IEEE802.11n HT20 @ 5GHz				
Mode	BPSK, QPSK, 16QAM, 64QAM and OFDM				
Channel	CH36 to CH165				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For antenna port	12	14	16	dBm	
2. Spectrum Mask @target power					
1) at fc +/-11MHz	-	-	-20	dBm	
2) at fc +/-20MHz	-	-	-28	dBm	
3) at fc > +/-30MHz	-	-	-45	dBm	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
6. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≤10%)	-	-	-82	dBm	
2) MCS1 (PER ≤10%)	-	-	-79	dBm	
3) MCS2 (PER ≤10%)	-	-	-77	dBm	
4) MCS3 (PER ≤10%)	-	-	-74	dBm	
5) MCS4 (PER ≤10%)	-	-	-70	dBm	
6) MCS5 (PER ≤10%)	-	-	-66	dBm	
7) MCS6 (PER ≤10%)	-	-	-65	dBm	
8) MCS7 (PER ≤10%)	-	-	-64	dBm	
6. Maximum Input Level (PER ≤10%)	-30	-	-	dBm	

9.7 IEEE 802.11n HT40 Section(5GHz)

Items	Contents
Specification	IEEE802.11n HT40 @ 5GHz

Mode	BPSK, QPSK, 16QAM, 64QAM and OFDM				
Channel	CH38 to CH163				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For antenna port	11	13	15	dBm	
2. Spectrum Mask @target power					
1) at fc +/-21MHz	-	-	-20	dB	
2) at fc +/-40MHz	-	-	-28	dB	
3) at fc > +/-60MHz	-	-	-45	dB	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
7. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≤10%)	-	-	-79	dBm	
2) MCS1 (PER ≤10%)	-	-	-76	dBm	
3) MCS2 (PER ≤10%)	-	-	-74	dBm	
4) MCS3 (PER ≤10%)	-	-	-71	dBm	
5) MCS4 (PER ≤10%)	-	-	-67	dBm	
6) MCS5 (PER ≤10%)	-	-	-63	dBm	
7) MCS6 (PER ≤10%)	-	-	-62	dBm	
8) MCS7 (PER ≤10%)	-	-	-61	dBm	
6. Maximum Input Level (PER ≤10%)	-30	-	-	dBm	

9.8 IEEE 802.11ac VHT20 Section(5GHz)

Items	Contents				
Specification	IEEE802.11ac				
Mode	BPSK, QPSK, 16QAM, 64QAM and OFDM				
Channel	CH36 to CH165				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					

1) For antenna port	12	14	16	dBm	
2. Spectrum Mask @target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-45	dBr	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
9) MCS8	-	-	-30	dB	
10) MCS9	-	-	-32	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
8. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≤10%)	-	-	-82	dBm	
2) MCS1 (PER ≤10%)	-	-	-79	dBm	
3) MCS2 (PER ≤10%)	-	-	-77	dBm	
4) MCS3 (PER ≤10%)	-	-	-74	dBm	
5) MCS4 (PER ≤10%)	-	-	-70	dBm	
6) MCS5 (PER ≤10%)	-	-	-66	dBm	
7) MCS6 (PER ≤10%)	-	-	-65	dBm	
8) MCS7 (PER ≤10%)	-	-	-64	dBm	
9) MCS8(PER ≤10%)			-59	dBm	
10) MCS9(PER ≤10%)			-57	dBm	
6. Maximum Input Level (PER ≤10%)	-30	-	-	dBm	

9.9 IEEE 802.11ac VHT40&80 Section(5GHz)

Items	Contents
Specification	IEEE802.11ac
Mode	BPSK, QPSK, 16QAM, 64QAM ,256QAM and OFDM
Channel	CH38 to CH163 VHT40 CH42 to CH157 VHT80

Data rate (MCS index)	MCS0/1/2/3/4/5/6/7/8/9				
	Min.	Typ.	Max.	Unit	Remark
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For antenna port	11	13	15	dBm	
2. Spectrum Mask @VHT20/VHT40/VHT80 target power					
1) at fc +/-11MHz/21MHz/41MHz	-	-	-20	dBr	
2) at fc +/-20MHz/40MHz/80MHz	-	-	-28	dBr	
3) at fc +/-30MHz/60MHz/120MHz	-	-	-40	dBr	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-27	dB	
9) MCS8	-	-	-30	dB	
10) MCS9	-	-	-32	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5. Minimum Input Level Sensitivity (each chain)			VHT40	VHT80	
1) MCS0 (PER ≤10%)	-	-	-79	-76	dBm
2) MCS1 (PER ≤10%)	-	-	-76	-73	dBm
3) MCS2 (PER ≤10%)	-	-	-74	-71	dBm
4) MCS3 (PER ≤10%)	-	-	-71	-68	dBm
5) MCS4 (PER ≤10%)	-	-	-67	-64	dBm
6) MCS5 (PER ≤10%)	-	-	-63	-60	dBm
7) MCS6 (PER ≤10%)	-	-	-62	-59	dBm
8) MCS7 (PER ≤10%)	-	-	-61	-58	dBm
9) MCS8 (PER ≤10%)	-	-	-56	-53	dBm
10) MCS9 (PER ≤10%)	-	-	-54	-51	dBm
6. Maximum Input Level (PER ≤10%)	-30	-	-	dBm	

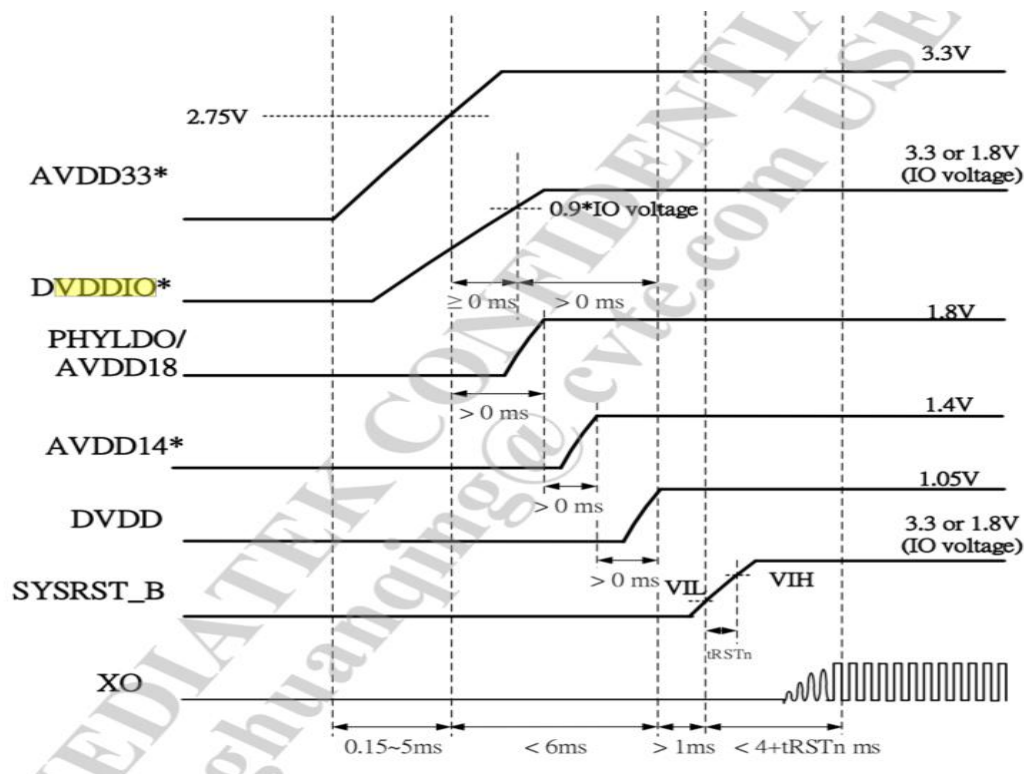
9.10 Bluetooth Section

Items	Contents
Specification	BT2.1+EDR/4.2/5.1

Mode	FHSS,GFSK,DPSK,DQPSK				
Number of Channel	79 Channels				
Frequency Band	2.402 GHz ~2.480GHz				
	Min.	Typ.	Max.	Unit	Remark
1. Output Power		4	-	dBm	
2. Gain step	2	4	8	dB	
3. Receiver sensitivity					
1). Enhanced data rate receiver specifications (BER $\leq 0.1\%$)	-	-86.5	-80	dBm	
2). Basic rate receiver specifications (BER $\leq 0.1\%$)	-	-93.5	-80	dBm	
3). Bluetooth LE receiver specifications (PER < 30.8%)	-	-93.5	-80	dBm	
4. Maximum usable signal (BER $\leq 0.1\%$)	-	-5	-		
5. C/I co-channel (BER<0.1%)	-	4	11	dB	
6. C/I 1MHz (BER<0.1%)	-	-14	0	dB	
7. C/I 2MHz (BER<0.1%)	-	-42	-30	dB	
8. C/I ≥ 3 MHz (BER<0.1%)	-	-49	-40	dB	
9. C/I Image channel (BER<0.1%)	-	-25	-9	dB	
10. C/I Image 1MHz (BER<0.1%)	-	-50	-20	dB	
11. Inter-modulation	-	-13	-	dB	
12. Out-of-band blocking					
1). 30MHz to 2000MHz	-10	-	-	dBm	
2). 2000MHz to 2399MHz	-27	-	-	dBm	
3). 2498MHz to 3000MHz	-27	-	-	dBm	
4). 3000MHz to 12.75GHz	-10	-	-	dBm	
13. Modulation characteristics					
1). Δf_{1avg}	140	157	175	KHz	
2). Δf_{2max} (For at least 99.9% of all Δf_{2max})	115	140	-	KHz	
3). $\Delta f_{1avg} / \Delta f_{2avg}$	0.8	0.98	-	KHz	
14. ICFT	-75	± 20	+75	KHz	
15. Carrier frequency drift					
1). One slot packet (DH1)	-25	± 15	+25	KHz	
2). Two slot packet (DH3)	-40	± 15	+40	KHz	
3). Five slot packet (DH5)	-40	± 15	+40	KHz	
4). Max drift rate	-	6	20	KHz/50us	
16. TX output spectrum(20dB bandwidth)	-	922	1000	KHz	
17. In-Band spurious emission					
1). ± 2 MHz offset	-	-45	-20	dBm	
2). ± 3 MHz offset	-	-48	-40	dBm	
3). $> \pm 3$ MHz offset	-	-48	-40	dBm	

10. Reference Design (参考设计)

10.1 Timing specification (时序规范)



注：模组时序，只需关注 3V3/RESET 时序，满足 AVDD33*/SYSRST_B

10.2 DC Electrical Characteristics (直流电气特性)

Symbol	Description	conditions	Min.	Typ.	Max.	Unit
VDD33	Power supplies	-	3.0	3.3	3.6	V
VDDIO	I/O input power supplies	-	3.0	3.3	3.6	V
I _{VDD33}	Power supply current	-	-	-	700	mA
V _{IH}	High-level input voltage	VDD33=3.3V	VDD33*0.625	-	VDD33+0.3	V
V _{IL}	Low-level input voltage	VDD33=3.3V	-0.3	-	VDD33*0.25	V
V _{OH}	High-level output voltage	VDD33=3.3V	VDD33-0.4	-	VDD33+0.3	V
V _{OL}	Low-level output voltage	VDD33=3.3V	-0.3	-	0.4	V
R _{PU}	Internal pull-up resistor	VDD33=3.3V	-	10	-	kΩ
R _{PD}	Internal pull-down resistor	VDD33=3.3V	40	75	190	kΩ

11. Mechanical, Environmental and Reliability Tests

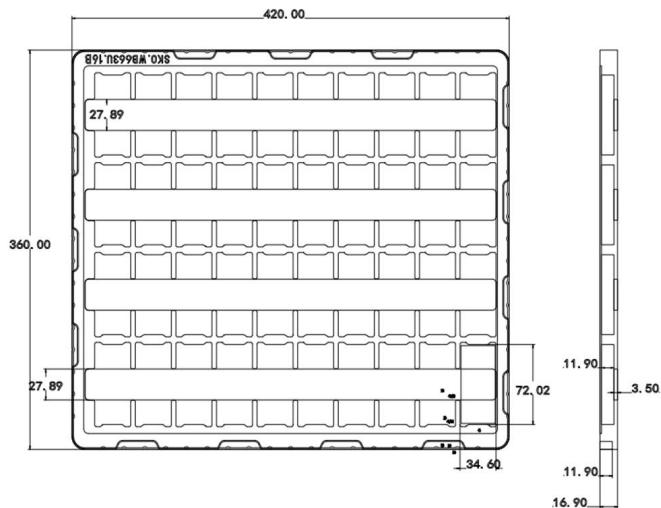
(机械、环境和可靠性测试)

Test Items		Test Conditions	Qty	Criteria Condition
11-1	Drop test	The packed samples was tested at below condition: Drop height: 760mm(0.5~9.5kg) 610mm(9.5~18.5kg) Drop time: 1x corner, 3x edge and 6x face.	1xBox	After test, the outer box and inner box will not been broken by appearance visual inspection, and the products should be ok.
11-2	Vibration test	X-Y-Z direction, first Frequency changing from 10Hz to 30Hz to 10Hz, amplitude 2.0mm, 5 times vibrations, 5x times vibration.	1xBox	After test, the outer box and inner box will not been broken by appearance visual inspection and the products should be ok.
11-3	Soldering ability test (Only for SKI module)	Soldering temperature: 245±5℃ Soldering duration: 3±0.5S	3	1. After soldering, the soldered area must be covered by a smooth bright solder layer, some deficiencies such as a small amount of the pinhole, not wetting are allowed, but the deficiencies can not be in the same place; 2. At least 90% of soldered area shall be covered continuously by the soldering material.
11-4	High Temperature and Humidity Operation Test	Leave samples in 60℃, 90% RH @ 24 hours	4	After test, the products appearance, power, EVM and frequency error functional parameter shall be satisfied with the test specification.
11-5	Low Temperature Operation Test	Leave samples in -15℃ @24 hours	4	After test, the products appearance, power, EVM and frequency error functional parameter shall be satisfied with the test specification.
11-6	High Temperature and Humidity Start Test	Leave samples in 60℃, 90% RH for 4x hours	4	After test, power on and off the samples for 3x tiems, the samples should be able to start normally

11-7	Low temperature start test	Leave samples in -15℃ for 4x hours	4	After test, power on and off the samples for 3x tiems, the samples should be able to start normally
11-8	High Temperature and Humidity Storage Test	Leave samples in 85℃, 95% RH @ 48 hours	4	After test, the products appearance, power, EVM and frequency error functional parameter shall be satisfied with the test specification.
11-9	Low Temperature Storage Test	Leave samples in -40℃, @48 hours	4	After test, the products appearance, power, EVM and frequency error functional parameter shall be satisfied with the test specification.
11-10	Thermal Shock Test	-40~85℃, dwell time: 30min, 50cycles	4	After test, the products appearance, power, EVM and frequency error functional parameter shall be satisfied with the test specification.
11-11	Aging Test	60℃, 120Hrs	10	The products at high temperature for a long time can continuous work normally
11-12	Salt spray test	NSS,35C,PH:6.5~7.2, 24H	2	The Sample shall has no minor or major defects, such as physical damage, crack, corrosion, deformation etc;
11-13	ESD	Discharge voltage: 1kV C: 50pF Discharge resistance: 330Ω Positive10 times 1 time for each second	3	The products can recoverable smoothly after ESD test.

12. Package (包装)

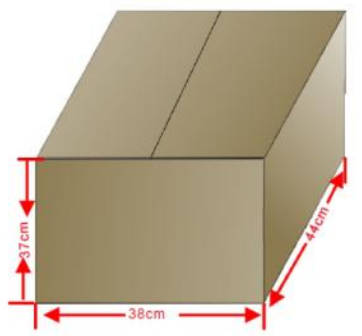
(1) 包装托盘示意图:



(2) 模组摆放位置



(3) 外箱尺寸: 44*37*37cm



(4) 包装数量

每盘包装 40 (10*4) 片, 每箱装 27 盘, 每箱数量=40*27=1080 PCS

FCC Statement:

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

List of applicable FCC rules

This module has been tested and found to comply with [part 15](#), [part 2](#) requirements for Modular Approval.

Antenna Placement Within the Host Platform

The module is tested for standalone mobile RF exposure use condition.

(1) The antenna must be installed such that 20 cm is maintained between the antenna and users,

(2) The transmitter module may not be co-located with any other transmitter or antenna.

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

The module complies with FCC Part 15.247 / Part 15.407 and apply for Single module

approval.

Trace antenna designs: Not applicable.

Any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify the module grantee that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the grantee, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application.

RF exposure considerations

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Antenna Type and Gain

The following antennas have been certified for use with this module.

Only antennas of the same type with equal or lower gain may also be used with this module. Other types of antennas and/or higher gain antennas may require the additional authorization for operation.

Antenna Specification list below:

Antenna Type	Frequency Bands	Max. Antenna Gain (dBi)
External Antenna (BT)	2.4GHz	2.77
External Antenna (WiFi)	2.4GHz	2.75
External Antenna (WiFi)	5GHz	5.35

End Product Labeling

When the module is installed in the host device, the FCC ID label must be visible through a window on the final device or it must be visible when an access panel, door or cover is easily re-moved. If not, a second label must be placed on the outside of the final device that contains the following text: “[Contains FCC ID: 2AR82-SKOWB663U16](#)”. The FCC ID can be used only when all FCC compliance requirements are met.

The end product shall bear the following 15.19 statement: This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) This device must accept any interference received, including interference that may cause undesired operation.

Information on test modes and additional testing requirements

This transmitter is tested in a standalone mobile RF exposure condition and any co-located or simultaneous transmission with other transmitter(s) class II permissive change re-evaluation or new certification.

Part 15 Subpart B disclaimer

This transmitter module is tested as a subsystem and its certification does not cover the FCC Part 15 Subpart B rule requirement applicable to the final host. The final host will still need to be reassessed for compliance to this portion of rule requirements if applicable.

As long as all conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Important Note

In the event that these conditions can not be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for reevaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The host integrator must follow the integration instructions provided in this document and ensure that the composite-system end product complies with the requirements by a technical assessment or evaluation to the rules and to KDB Publication 996369.

The host integrator installing this module into their product must ensure that the final composite product complies with the requirements by a technical assessment or evaluation to the rules, including the transmitter operation and should refer to guidance in KDB 996369.

OEM/Host manufacturer responsibilities

OEM/Host manufacturers are ultimately responsible for the compliance of the Host and Module. The final product must be reassessed against all the essential requirements of the FCC rule such as FCC Part 15 Subpart B before it can be placed on the US market. This includes reassessing the transmitter module for compliance with the Radio and EMF essential requirements of the FCC rules. This module must not be incorporated into any other device or system without retesting for compliance as multi-radio and combined equipment

According to country code, channel 12 and 13 would be disabled in North America.